Product / Package Information

Package	MQFP_PQ4
Body Size (mm)	32 X 32 X 3.5 (+2.6)
Lead Count	240
Terminal Finish	100 Sn
MS Number	MS011415B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.83E+00	86.91	869100	45.73	457282
Thermosets	Epoxy & Phenol Resin	Proprietary	5.63E-01	12.78	127800	6.72	67243
Other inorganic materials	Carbon black	1333-86-4	1.37E-02	0.31	3100	0.16	1631
Subtotal			4.41 E+00	100.00	1000000	52.62	526156

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.61 E-01	99.25	992500	11.47	114708
Copper & its alloys	Chromium	7440-47-3	2.90 E-03	0.30	3000	0.03	347
Copper & its alloys	Tin	7440-31-5	2.42 E-03	0.25	2500	0.03	289
Copper & its alloys	Zinc	7440-66-6	1.94 E-03	0.20	2000	0.02	231
Subtotal			9.68 E-01	100.00	1000000	11.56	115575

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.86 E-03	100.0	1000000	0.03	342

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.46 E-02	100.0	1000000	0.41	4133

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.06 E-02	100.0	1000000	0.25	2459

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.88 E-01	100.0	1000000	3.44	34409

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.85 E-02	73.54	735400	0.22	2208
Other organic materials	Epoxy resin A	TS ref# 10013	1.85 E-03	7.35	73500	0.02	221
Others	Anhydride	TS ref# 10181	1.85 E-03	7.35	73500	0.02	221
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	7.39 E-04	2.94	29400	0.01	88
Other organic materials	Epoxy resin B	TS ref# 10237	7.39 E-04	2.94	29400	0.01	88
Others	Epoxy resin modifier	TS ref# 10038	7.39 E-04	2.94	29400	0.01	88
Others	Anhydride	TS ref# 10180	7.39 E-04	2.94	29400	0.01	88
Subtotal			2.52 E-02	100.0	1000000	0.30	3003

Heat Sink

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Aluminum & its alloys	Aluminum	7429-90-5	2.63 E+00	100.00	1.00 E+06	31.39	313924

	Weight (g)	Percentage (%)	PPM
Package Totals	**8.37 E+00**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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